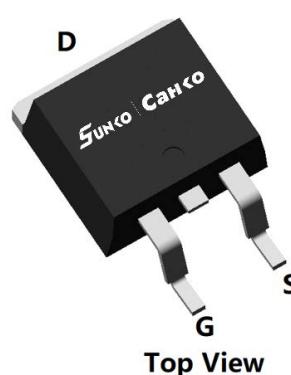
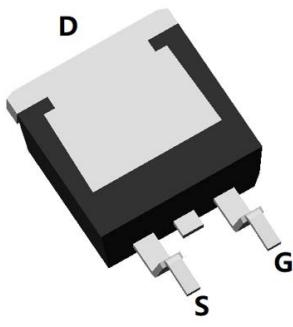


## N-Channel Enhancement Mode Field Effect Transistor

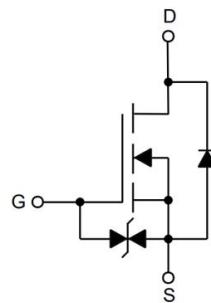


Top View



Bottom View

TO-263



### Product Summary

- $V_{DS}$  60V
- $I_D$  200A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) <2.9 mohm
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) <3.9 mohm
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Consumer electronic power supply
- Isolated DC-DC Converters
- Motor control
- Invertors

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		$V_{DS}$	60	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current <sup>A</sup>	$T_c=25^\circ C$	$I_D$	200	A
	$T_c=100^\circ C$		125	
Pulsed Drain Current <sup>B</sup>		$I_{DM}$	600	A
Avalanche energy <sup>C</sup>		$E_{AS}$	506	mJ
Total Power Dissipation <sup>D</sup>		$P_D$	260	W
Thermal Resistance Junction-to-Case		$R_{\theta JC}$	0.48	$^\circ C/W$
Thermal Resistance Junction-to-Ambient <sup>E</sup>		$R_{\theta JA}$	28	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ C$

### Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
SCB200G06C	F2	SCB200G06C	800	/	8000	13" reel

■ Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.6	2.2	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=20\text{A}$		2.35	2.9	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=15\text{A}$		2.9	3.9	
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
Maximum Body-Diode Continuous Current	$I_{\text{S}}$				200	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=100\text{KHZ}$		5950		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			1250		
Reverse Transfer Capacitance	$C_{\text{rss}}$			85		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=50\text{A}$		93		$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$			17		
Gate-Drain Charge	$Q_{\text{gd}}$			14		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_{\text{F}}=25\text{A}, di/dt=100\text{A/us}$		73		$\text{ns}$
Reverse Recovery Time	$t_{\text{rr}}$			68		
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=30\text{V}, I_{\text{D}}=25\text{A}$ $R_{\text{GEN}}=2\Omega$		22.5		$\text{ns}$
Turn-on Rise Time	$t_r$			6.7		
Turn-off Delay Time	$t_{\text{d(off)}}$			80.3		
Turn-off fall Time	$t_f$			26.9		

**Note:**

- A. The maximum current rating is package limited.
- B. Repetitive rating; pulse width limited by max. junction temperature.
- C.  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=80\text{V}$ ,  $V_G=10\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=45\text{A}$ .
- D.  $P_D$  is based on max. junction temperature, using junction-case thermal resistance.
- E. The value of  $R_{\text{GJA}}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .

## ■ Typical Performance Characteristics

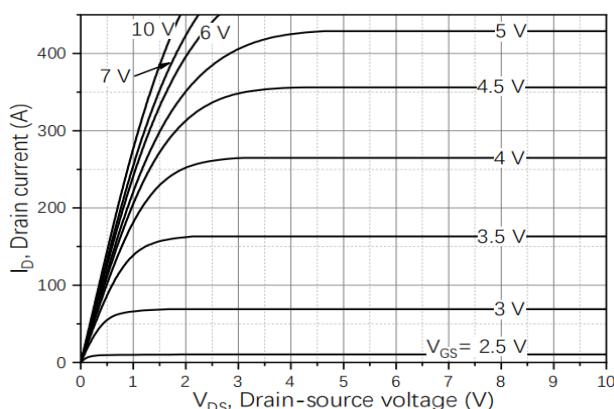


Figure1. Output Characteristics

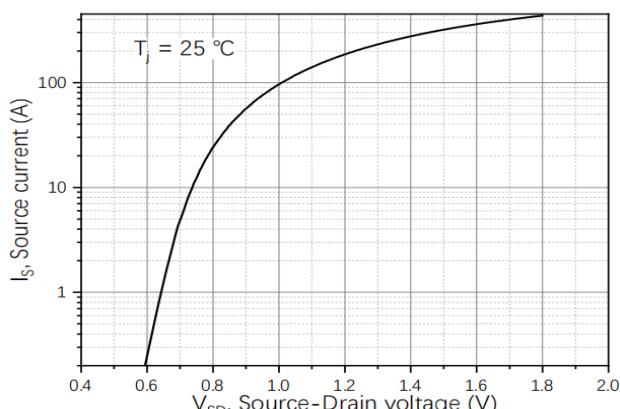


Figure2. Transfer Characteristics

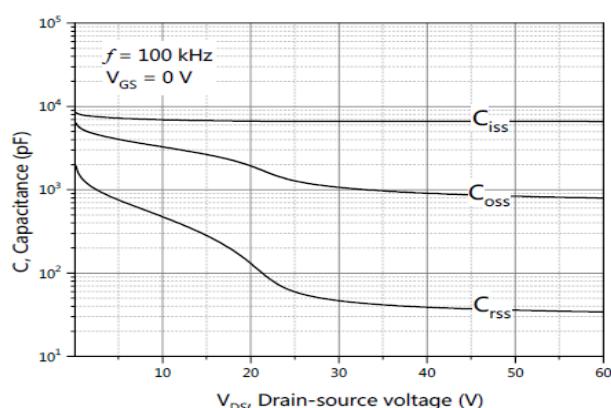


Figure3. Capacitance Characteristics

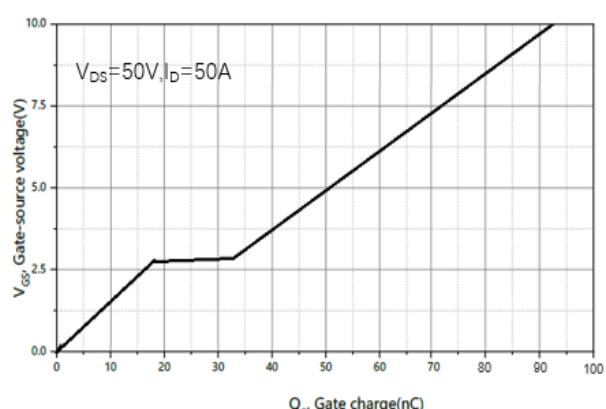


Figure4. Gate Charge

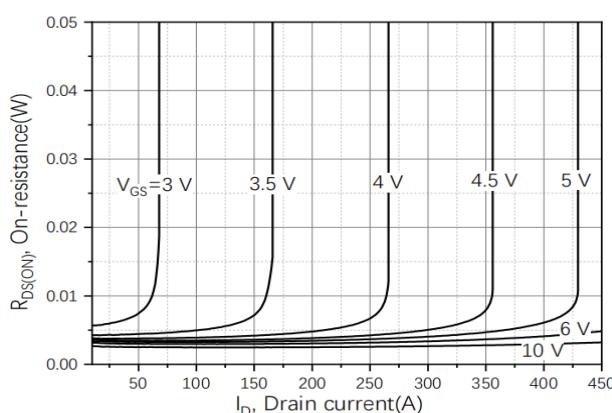


Figure5. Drain-Source on Resistance

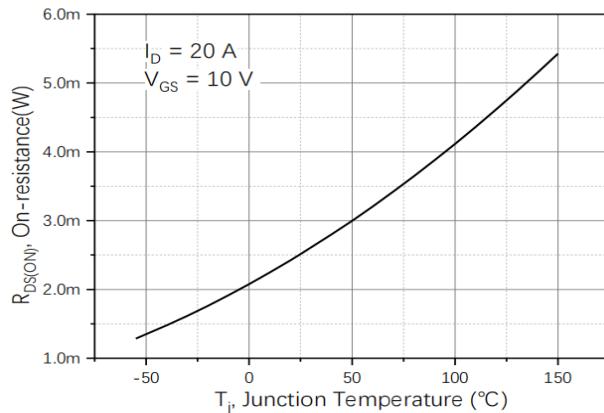


Figure6. Drain-Source on Resistance

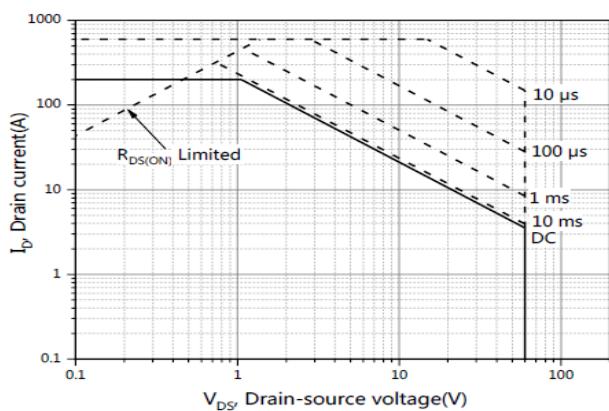


Figure7. Safe Operation Area

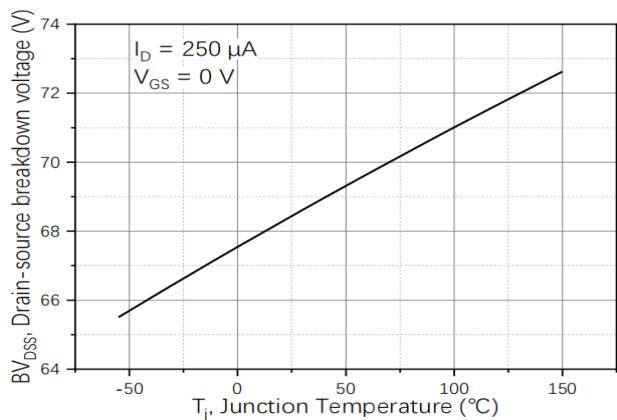


Figure8. Drain-source breakdown voltage

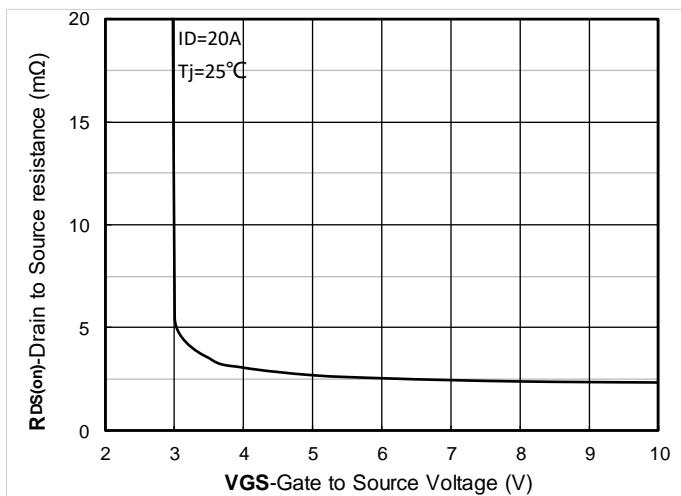


Figure9. On-Resistance vs Gate to Source Voltage

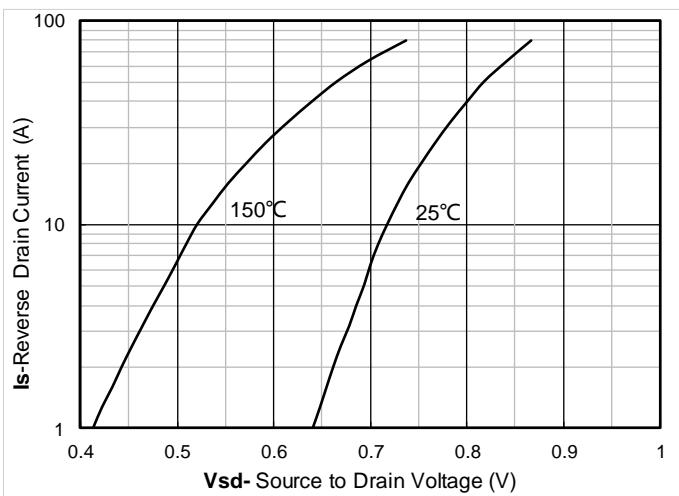


Figure10. Forward characteristics of reverse diode

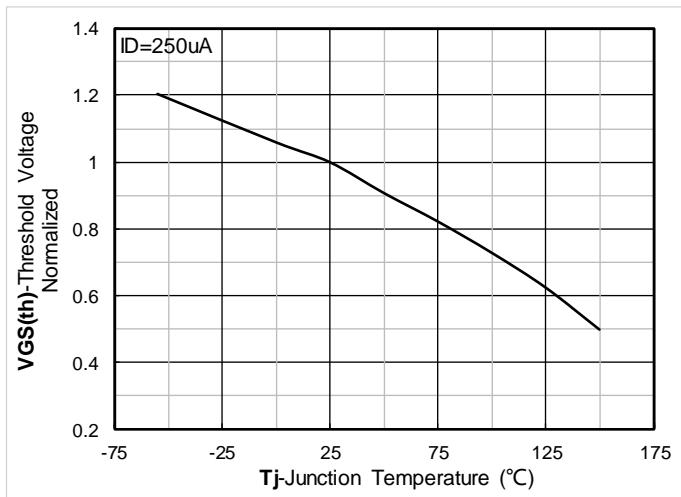


Figure11. Normalized Threshold voltage

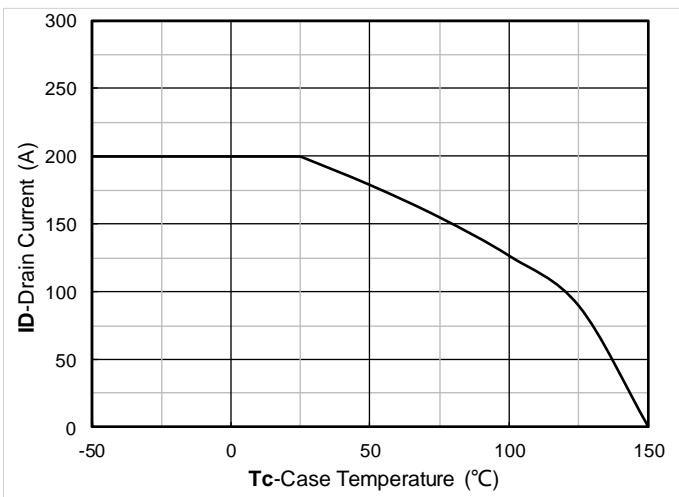


Figure12. Current dissipation

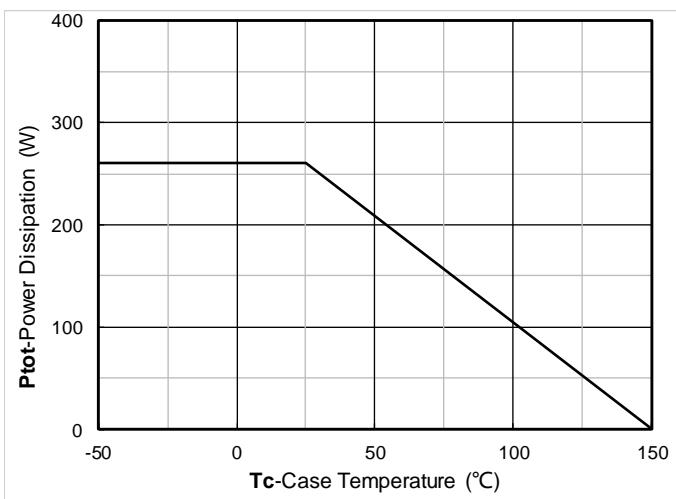


Figure13. Power dissipation

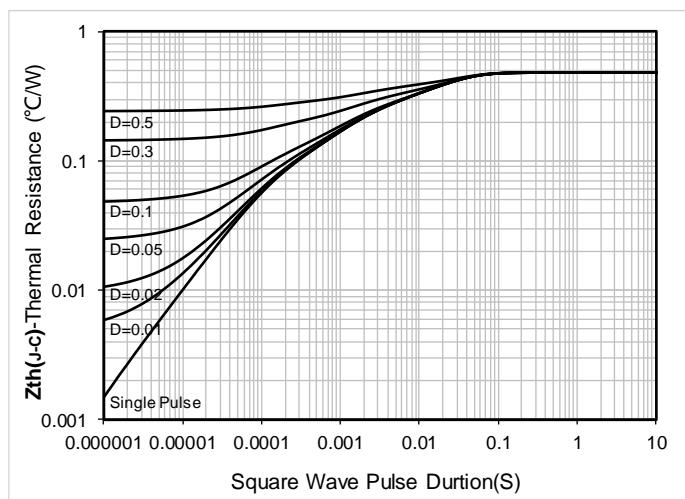


Figure14. Maximum Transient Thermal Impedance

## ■ Test circuits and waveforms

Figure A: Gate Charge Test Circuit &amp; Waveforms

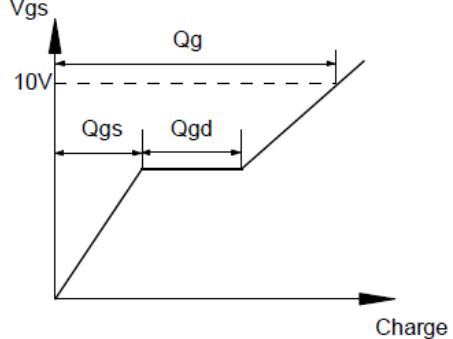
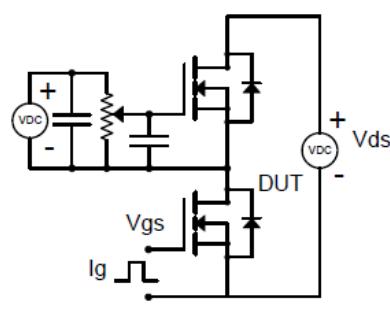


Figure B: Resistive Switching Test Circuit &amp; Waveforms

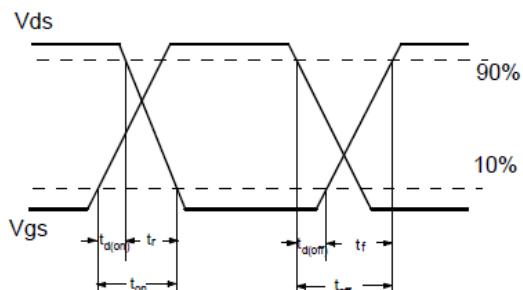
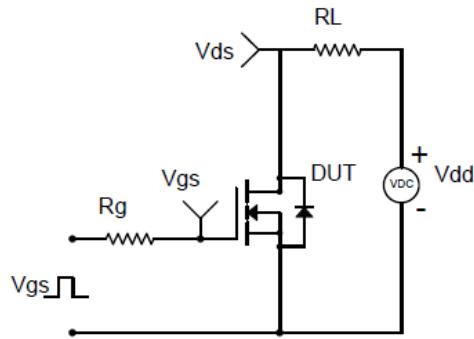


Figure C: Unclamped Inductive Switching (UIS) Test

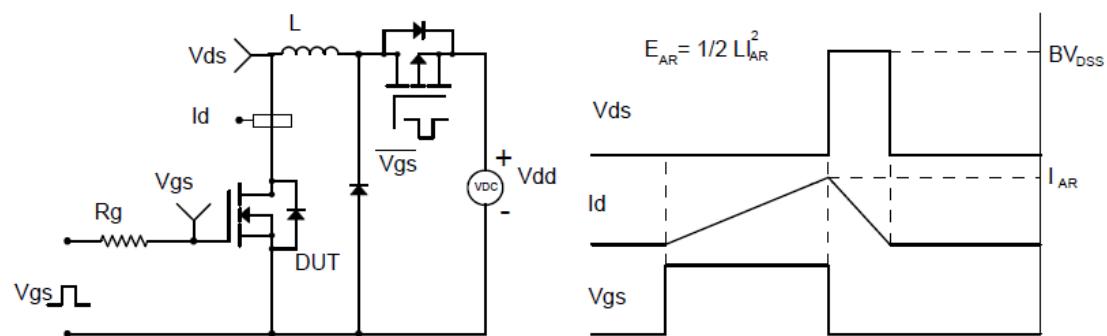
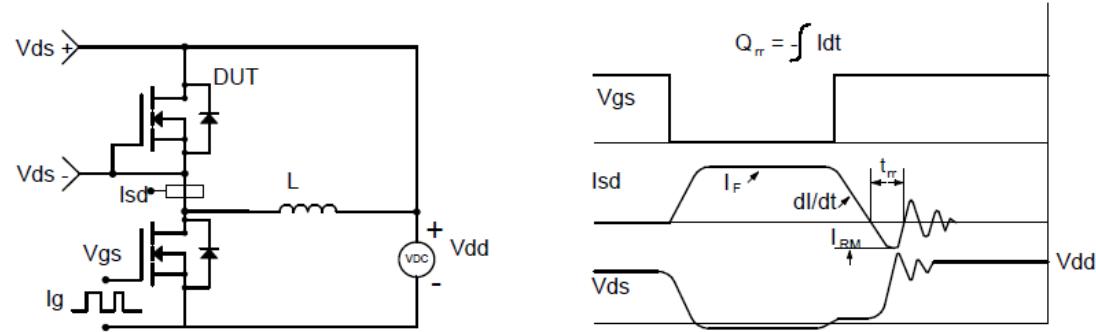
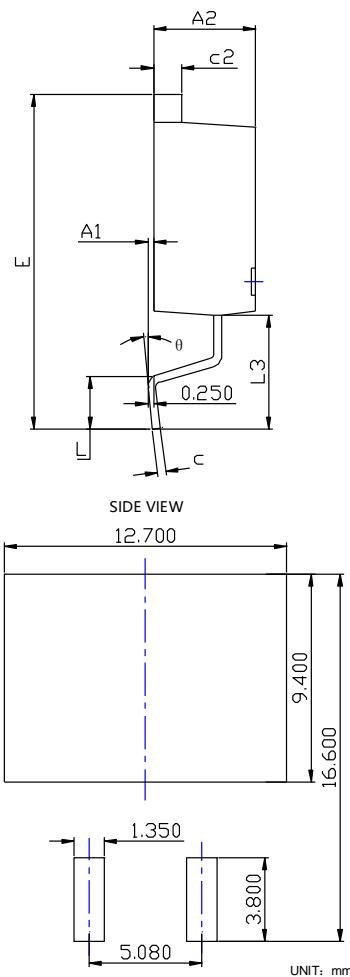
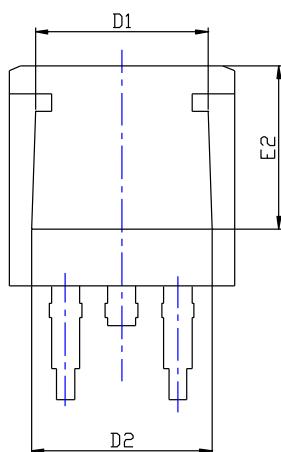
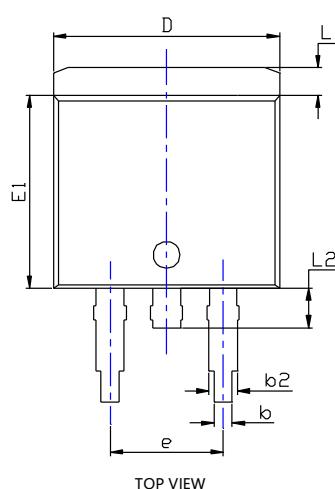


Figure D: Diode Recovery Test Circuit &amp; Waveforms



## ■ TO-263-HY Package information



SUGGESTED SOLDER PAD LAYOUT

SYMBOL	INCHES			Millimeter		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A1	0.000	---	0.010	0.000	---	0.250
A2	0.174	0.180	0.186	4.430	4.580	4.730
b	0.028	0.032	0.036	0.720	0.820	0.920
b2	0.046	0.050	0.054	1.180	1.280	1.380
c	0.013	0.015	0.018	0.330	0.390	0.450
c2	0.048	0.050	0.053	1.220	1.280	1.340
D	0.394	0.400	0.406	10.000	10.150	10.300
D1	0.295	0.307	0.319	7.500	7.800	8.100
D2	0.303	0.315	0.327	7.700	8.000	8.300
E	0.571	0.591	0.610	14.500	15.000	15.500
E1	0.337	0.341	0.348	8.550	8.700	8.850
E2	0.276	0.287	0.299	7.000	7.300	7.600
e	0.200BSC			5.080BSC		
L	0.070	---	0.110	1.790	---	2.790
L1	0.044	---	0.056	1.120	---	1.420
L2	0.030	---	0.070	0.770	---	1.770
L3	0.197REF			5.000REF		
θ	0°	---	8°	0°	---	8°

## NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.

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